











LMV431, LMV431A, LMV431B

SNVS041G-MAY 2004-REVISED SEPTEMBER 2014

LMV431x Low-Voltage (1.24-V) Adjustable Precision Shunt Regulators

Features

- Low-Voltage Operation/Wide Adjust Range (1.24 V/30 V)
- 0.5% Initial Tolerance (LMV431B)
- Temperature Compensated for Industrial Temperature Range (39 PPM/°C for the LMV431AI)
- Low Operation Current (55 µA)
- Low Output Impedance (0.25 Ω)
- Fast Turn-On Response
- Low Cost

Applications

- **Shunt Regulator**
- Series Regulator
- Current Source or Sink
- Voltage Monitor
- **Error Amplifier**
- 3-V Off-Line Switching Regulator
- Low Dropout N-Channel Series Regulator

3 Description

The LMV431, LMV431A and LMV431B are precision 1.24 V shunt regulators capable of adjustment to 30 V. Negative feedback from the cathode to the adjust pin controls the cathode voltage, much like a noninverting op amp configuration (Refer to Symbol and Functional Diagrams). A two-resistor voltage divider terminated at the adjust pin controls the gain of a 1.24 V band-gap reference. Shorting the cathode to the adjust pin (voltage follower) provides a cathode voltage of a 1.24 V.

The LMV431, LMV431A and LMV431B have respective initial tolerances of 1.5%, 1%, and 0.5%, and functionally lend themselves to several applications that require zener diode performance at low voltages. Applications include a 3 V to 2.7 V low drop-out regulator, an error amplifier in a 3 V off-line switching regulator and even as a voltage detector. These parts are typically stable with capacitive loads greater than 10 nF and less than 50 pF.

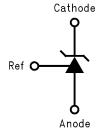
The LMV431, LMV431A and LMV431B provide performance at a competitive price.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)			
LMV431	SOT-23 (5)	2.90 mm x 1.60 mm			
LMV431	TO-92 (3)	4.30 mm x 4.30 mm			
LMV431	SOT-23 (3)	2.92 mm x 1.30 mm			

(1) For all available packages, see the orderable addendum at the end of the datasheet.

4 Symbol and Functional Diagrams



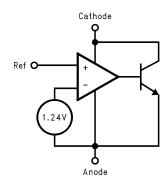




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5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision F (May 2005) to Revision G

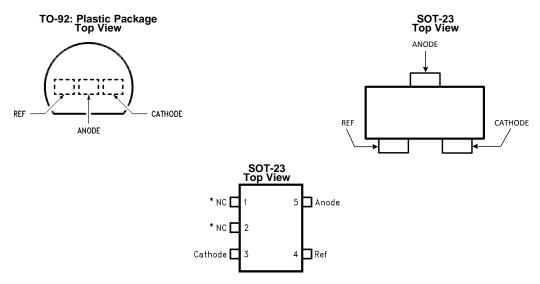
Page

- Changed formatting to match new TI datasheet guidelines; added Device Information and Handling Ratings tables,
 Layout, and Device and Documentation Support sections; reformatted Detailed Description and Application and Implementation sections.

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6 Pin Configurations and Functions



^{*}Pin 1 is not internally connected.

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^{*}Pin 2 is internally connected to Anode pin. Pin 2 should be either floating or connected to Anode pin.



7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
On a rating tamparatura	Industrial (LMV431AI, LMV431I)	-40	85	
Operating temperature	Commercial (LMV431AC, LMV431C, LMV431BC)	0	70	°C
Lead temperature	TO-92 Package/SOT-23 -5,-3 Package (Soldering, 10 sec.)		265	Ü
Internal power dissipation ⁽²⁾	TO-92		0.78	W
	SOT-23-5, -3 Package		0.28	W
Cathode voltage			35	V
Continuous cathode current		-30	30	Α
Reference input current		05	3	mA

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 Handling Ratings

			MIN	MAX	UNIT
T _{stg}	Storage temperature range		- 65	150	°C
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾		2000	V

⁽¹⁾ The human body model is a 100 pF capacitor discharged through a 1.5kΩ resistor into each pin. The machine model is a 200 pF capacitor discharged directly into each pin. MIL-STD-883 3015.7.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM MAX	UNIT
Cathode voltage		V_{REF}	30	V
Cathode current	athode current		15	mA
Temperature	LMV431AI	-40	85	°C
Derating Curve (Slope = −1/R _{θJA})				

7.4 Thermal Information

		LMV431	LMV431	LMV431	
	THERMAL METRIC ⁽¹⁾	SOT-23	SOT-23	TO-92	UNIT
		3 PINS	5 PINS	3 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance (2)	455	455	161	°C/W

⁽¹⁾ For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

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⁽²⁾ Ratings apply to ambient temperature at 25°C. Above this temperature, derate the TO-92 at 6.2 mW/°C, and the SOT-23-5 at 2.2 mW/°C. See derating curve in Operating Condition section.

⁽²⁾ $T_{J \text{ Max}} = 150^{\circ}\text{C}$, $T_{J} = T_{A} + (R_{\theta JA} P_{D})$, where P_{D} is the operating power of the device.

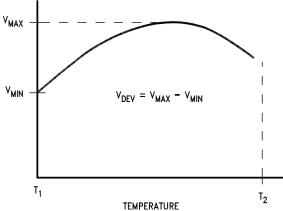


7.5 LMV431C Electrical Characteristics

T_A = 25°C unless otherwise specified

SYMBOL	PARAMETER	TEST CONDI	TIONS	MIN	TYP	MAX	UNIT
.,	Deference Valtere	$V_7 = V_{REE}, I_7 = 10 \text{ mA}$	T _A = 25°C	1.222	1.24	1.258	V
V_{REF}	Reference Voltage	(See Figure 32)	T _A = Full Range	1.21		1.27	V
V _{DEV}	Deviation of Reference Input Voltage Over Temperature ⁽¹⁾	$V_Z = V_{REF}$, $I_Z = 10$ mA, $T_A = Full Range (See Figure)$	re 32)		4	12	mV
$\frac{\Delta V_{REF}}{\Delta V_{Z}}$	Ratio of the Change in Reference Voltage to the Change in Cathode Voltage	\overline{V}_Z from V_{REF} to 6 \overline{V}	I_Z = 10 mA (see Figure 33) V_Z from V_{REF} to 6 V R_1 = 10 kΩ, R_2 = ∞ and 2.6 kΩ		-1.5	-2.7	mV/V
I _{REF}	Reference Input Current	R_1 = 10 kΩ, R_2 = ∞ I_1 = 10 mA (see Figure 33)			0.15	0.5	μΑ
∝I _{REF}	Deviation of Reference Input Current over Temperature	$R_1 = 10 \text{ k}\Omega, R_2 = \infty,$ $I_1 = 10 \text{ mA}, T_A = \text{Full Range}$	e (see Figure 33)		0.05	0.3	μΑ
I _{Z(MIN)}	Minimum Cathode Current for Regulation	V _Z = V _{REF} (see Figure 32)			55	80	μΑ
I _{Z(OFF)}	Off-State Current	V _Z = 6 V, V _{REF} = 0 V (see F	igure 34)		0.001	0.1	μΑ
r _Z	Dynamic Output Impedance (2)	$V_Z = V_{REF}$, $I_Z = 0.1$ mA to 1 Frequency = 0 Hz (see Figure 1)			0.25	0.4	Ω

(1) Deviation of reference input voltage, V_{DEV}, is defined as the maximum variation of the reference input voltage over the full temperature range. See the following:



The average temperature coefficient of the reference input voltage, «V_{REF}, is defined as:

$$\propto V_{REF} \frac{ppm}{{}^{\circ}\!C} = \frac{\pm \left(\frac{V_{Max} - V_{Min}}{V_{REF}(at\ 25{}^{\circ}\!C)}\right) 10^{6}}{T_{2} - T_{1}} = \frac{\pm \left(\frac{V_{DEV}}{V_{REF}(at\ 25{}^{\circ}\!C)}\right) 10^{6}}{T_{2} - T_{1}}$$

Where: $T_2 - T_1$ = full temperature change. ${}^{\propto}V_{REF}$ can be positive or negative depending on whether the slope is positive or negative. Example: $V_{DEV} = 6$ mV, $V_{REF} = 1240$ mV, $T_2 - T_1 = 125$ °C.

$$\propto V_{REF} = \frac{\left(\frac{6.0 \text{ mV}}{1240 \text{ mV}}\right) 10^6}{125 \text{ °C}} = +39 \text{ ppm / °C}$$

(2) The dynamic output impedance, r_Z, is defined as:

$$r_Z = \frac{\Delta v_Z}{\Delta l_Z}$$

When the device is programmed with two external resistors, R1 and R2, (see *Figure 33*), the dynamic output impedance of the overall circuit, r_Z, is defined as:

$$r_Z = \frac{\Delta V_Z}{\Delta I_Z} \cong \left[r_Z \left(1 + \frac{R1}{R2} \right) \right]$$

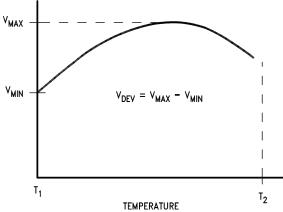


7.6 LMV431I Electrical Characteristics

 $T_A = 25$ °C unless otherwise specified

SYMBOL	PARAMETER	TEST CONDITION	IS	MIN	TYP	MAX	UNIT
V _{REF}	Reference Voltage	$V_Z = V_{REF}$, $I_Z = 10 \text{ mA}$	T _A = 25°C	1.222	1.24	1.258	
		(See Figure 32)	T _A = Full Range	1.202		1.278	V
V _{DEV}	Deviation of Reference Input Voltage Over Temperature (1)	$V_Z = V_{REF}$, $I_Z = 10$ mA, $T_A = Full$ Range (See Figure 32)			6	20	mV
$\frac{\Delta V_{REF}}{\Delta V_{Z}}$	Ratio of the Change in Reference Voltage to the Change in Cathode Voltage	I_Z = 10mA (see Figure 33) V_Z from V_{REF} to 6V R_1 = 10 kΩ, R_2 = ∞ and 2.6kΩ			-1.5	-2.7	mV/V
I _{REF}	Reference Input Current	$R_1 = 10 \text{ k}\Omega, R_2 = \infty$ $I_1 = 10 \text{ mA (see Figure 33)}$			0.15	0.5	μΑ
∝I _{REF}	Deviation of Reference Input Current over Temperature	$R_1 = 10 \text{ k}\Omega, R_2 = \infty,$ $I_1 = 10 \text{ mA}, T_A = Full Range (see$	Figure 33)		0.1	0.4	μΑ
I _{Z(MIN)}	Minimum Cathode Current for Regulation	$V_Z = V_{REF}(see Figure 32)$			55	80	μΑ
I _{Z(OFF)}	Off-State Current	V _Z = 6 V, V _{REF} = 0V (see Figure	34)	·	0.001	0.1	μΑ
r _Z	Dynamic Output Impedance ⁽²⁾	$V_Z = V_{REF}$, $I_Z = 0.1$ mA to 15 mA Frequency = 0 Hz (see Figure 32)			0.25	0.4	Ω

(1) Deviation of reference input voltage, V_{DEV}, is defined as the maximum variation of the reference input voltage over the full temperature range. See the following:



The average temperature coefficient of the reference input voltage, «V_{REF}, is defined as:

$$\propto V_{REF} \frac{ppm}{^{\circ}C} = \frac{\pm \left(\frac{V_{Max} - V_{Min}}{V_{REF}(at\ 25^{\circ}C)}\right) 10^{6}}{T_{2} - T_{1}} = \frac{\pm \left(\frac{V_{DEV}}{V_{REF}(at\ 25^{\circ}C)}\right) 10^{6}}{T_{2} - T_{1}}$$

Where: $T_2 - T_1$ = full temperature change. ${}^{\alpha}V_{REF}$ can be positive or negative depending on whether the slope is positive or negative. Example: $V_{DEV} = 6$ mV, $V_{REF} = 1240$ mV, $T_2 - T_1 = 125$ °C.

$$\propto V_{REF} = \frac{\left(\frac{6.0 \text{ mV}}{1240 \text{ mV}}\right) 10^6}{125^{\circ}\text{C}} = +39 \text{ ppm/}^{\circ}\text{C}$$

(2) The dynamic output impedance, r_Z , is defined as: $r_Z = \frac{\Delta V_Z}{r_Z}$

$$r_Z = \frac{\Delta v_Z}{\Delta l_Z}$$

When the device is programmed with two external resistors, R1 and R2, (see *Figure 33*), the dynamic output impedance of the overall circuit, r_Z, is defined as:

$$r_Z = \frac{\Delta V_Z}{\Delta I_Z} \cong \left[r_Z \left(1 + \frac{R1}{R2} \right) \right]$$

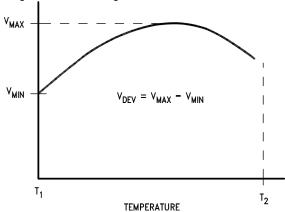


7.7 LMV431AC Electrical Characteristics

T_A = 25°C unless otherwise specified

SYMBOL	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V _{REF}	Reference Voltage	$V_Z = V_{REF}$, $I_Z = 10 \text{ mA}$	T _A = 25°C	1.228	1.24	1.252	V
		(See Figure 32)	T _A = Full Range	1.221		1.259	V
V _{DEV}	Deviation of Reference Input Voltage Over Temperature ⁽¹⁾	$V_Z = V_{REF}$, $I_Z = 10$ mA, $T_A = Full Range (See Figure)$	32)		4	12	mV
$\frac{\Delta V_{REF}}{\Delta V_{Z}}$	Ratio of the Change in Reference Voltage to the Change in Cathode Voltage	I_Z = 10 mA (see Figure 33) V_Z from V_{REF} to 6 V R_1 = 10 kΩ, R_2 = ∞ and 2.6 kΩ			-1.5	-2.7	mV/V
I _{REF}	Reference Input Current	R_1 = 1 kΩ, R_2 = ∞ I_1 = 10 mA (see Figure 33)			0.15	0.50	μΑ
∝I _{REF}	Deviation of Reference Input Current over Temperature	$R_1 = 10 \text{ k}\Omega, R_2 = \infty,$ $I_1 = 10 \text{ mA}, T_A = \text{Full Range}$	$R_1 = 10 \text{ k}\Omega, R_2 = \infty,$ $I_1 = 10 \text{ mA}, T_A = \text{Full Range (see Figure 33)}$		0.05	0.3	μΑ
I _{Z(MIN)}	Minimum Cathode Current for Regulation	V _Z = V _{REF} (see Figure 32)			55	80	μΑ
I _{Z(OFF)}	Off-State Current	$V_Z = 6 \text{ V}, V_{REF} = 0 \text{V}$ (see Fig	gure 34)		0.001	0.1	μΑ
r_Z	Dynamic Output Impedance (2)	$V_Z = V_{REF}$, $I_Z = 0.1$ mA to 15mA Frequency = 0 Hz (see Figure 32)			0.25	0.4	Ω

(1) Deviation of reference input voltage, V_{DEV}, is defined as the maximum variation of the reference input voltage over the full temperature range. See the following:



The average temperature coefficient of the reference input voltage, ${\scriptscriptstyle \propto} V_{REF}$, is defined as:

$$\propto V_{REF} \frac{ppm}{{}^{\circ}C} = \frac{\pm \left(\frac{V_{Max} - V_{Min}}{V_{REF}(at\ 25{}^{\circ}C)}\right) 10^{6}}{T_{2} - T_{1}} = \frac{\pm \left(\frac{V_{DEV}}{V_{REF}(at\ 25{}^{\circ}C)}\right) 10^{6}}{T_{2} - T_{1}}$$

Where: $T_2 - T_1$ = full temperature change. ${}^{\sim}V_{REF}$ can be positive or negative depending on whether the slope is positive or negative. Example: $V_{DEV} = 6 \text{ mV}$, $V_{REF} = 1240 \text{ mV}$, $T_2 - T_1 = 125 {}^{\circ}C$.

$$\propto V_{REF} = \frac{\left(\frac{6.0 \text{ mV}}{1240 \text{ mV}}\right) 10^6}{125^{\circ}\text{C}} = +39 \text{ ppm} / {^{\circ}\text{C}}$$

(2) The dynamic output impedance, rz, is defined as:

$$r_Z = \frac{\Delta v_Z}{\Delta l_Z}$$

When the device is programmed with two external resistors, R1 and R2, (see *Figure 33*), the dynamic output impedance of the overall circuit, r_z, is defined as:

$$r_Z = \frac{\Delta V_Z}{\Delta I_Z} \cong \left[r_Z \left(1 + \frac{R1}{R2} \right) \right]$$

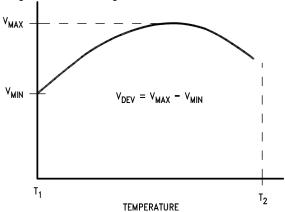


7.8 LMV431Al Electrical Characteristics

 $T_{\Lambda} = 25^{\circ}C$ unless otherwise specified

SYMBOL	PARAMETER	TEST CONDITI	ONS	MIN	TYP	MAX	UNIT
	Deference Voltage	$V_Z = V_{REF}$, $I_Z = 10mA$	T _A = 25°C	1.228	1.24	1.252	V
V_{REF}	Reference Voltage	(See Figure 32)	T _A = Full Range	1.215		1.265	V
V _{DEV}	Deviation of Reference Input Voltage Over Temperature ⁽¹⁾	$V_Z = V_{REF}$, $I_Z = 10$ mA, $T_A = Full Range (See Figure)$	32)		6	20	mV
$\frac{\Delta V_{REF}}{\Delta V_{Z}}$	Ratio of the Change in Reference Voltage to the Change in Cathode Voltage	I_Z = 10mA (see Figure 33) V_Z from V_{REF} to 6 V R_1 = 10 kΩ, R_2 = ∞ and 2.6 kΩ			-1.5	-2.7	mV/V
I _{REF}	Reference Input Current	$R_1 = 10 \text{ k}\Omega, R_2 = \infty$ $I_1 = 10 \text{ mA (see Figure 33)}$			0.15	0.5	μΑ
∝I _{REF}	Deviation of Reference Input Current over Temperature	$R_1 = 10 \text{ k}\Omega$, $R_2 = \infty$, $I_1 = 10 \text{ mA}$, $T_A = \text{Full Range (see Figure 33)}$			0.1	0.4	μΑ
I _{Z(MIN)}	Minimum Cathode Current for Regulation	V _Z = V _{REF} (see Figure 32)			55	80	μΑ
I _{Z(OFF)}	Off-State Current	$V_Z = 6 \text{ V}, V_{REF} = 0 \text{ V}$ (see Fig.	gure 34)		0.001	0.1	μΑ
r _Z	Dynamic Output Impedance (2)	$V_z = V_{REF}$, $I_z = 0.1$ mA to 15 mA Frequency = 0 Hz (see Figure 32)			0.25	0.4	Ω

Deviation of reference input voltage, V_{DEV}, is defined as the maximum variation of the reference input voltage over the full temperature range. See the following:



The average temperature coefficient of the reference input voltage,
$${}_{\alpha}V_{REF}$$
, is defined as:
$${}_{\infty}V_{REF} \frac{ppm}{{}^{\circ}C} = \frac{\pm \left(\frac{V_{Max} - V_{Min}}{V_{REF}(at\ 25{}^{\circ}C)}\right) 10^6}{T_2 - T_1} = \frac{\pm \left(\frac{V_{DEV}}{V_{REF}(at\ 25{}^{\circ}C)}\right) 10^6}{T_2 - T_1}$$

Where: $T_2 - T_1$ = full temperature change. ${}^{\sim}V_{REF}$ can be positive or negative depending on whether the slope is positive or negative. Example: $V_{DEV} = 6$ mV, $V_{REF} = 1240$ mV, $T_2 - T_1 = 125$ °C. ${}^{\sim}V_{REF} = \frac{\left(\frac{6.0 \text{ mV}}{1240 \text{ mV}}\right) 10^6}{125^{\circ}C} = +39 \text{ ppm} / {}^{\circ}C$

$$\propto V_{REF} = \frac{\left(\frac{6.0 \text{ mV}}{1240 \text{ mV}}\right) 10^6}{125^{\circ}\text{C}} = +39 \text{ ppm} / {^{\circ}\text{C}}$$

(2) The dynamic output impedance, r_Z, is defined as:

$$r_Z = \frac{\Delta v_Z}{\Delta l_Z}$$

When the device is programmed with two external resistors, R1 and R2, (see Figure 33), the dynamic output impedance of the overall circuit, rz, is defined as:

$$r_Z = \frac{\Delta V_Z}{\Delta I_Z} \cong \left[r_Z \left(1 + \frac{R1}{R2} \right) \right]$$

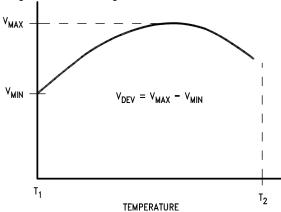


7.9 LMV431BC Electrical Characteristics

 $T_{\Delta} = 25^{\circ}C$ unless otherwise specified

SYMBOL	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
\/	Peteronee Voltege	$V_Z = V_{REF}$, $I_Z = 10 \text{ mA}$	T _A = 25°C	1.234	1.24	1.246	V
V_{REF}	Reference Voltage	(See Figure 32)	T _A = Full Range	1.227		1.253	V
V _{DEV}	Deviation of Reference Input Voltage Over Temperature ⁽¹⁾	$V_Z = V_{REF}$, $I_Z = 10$ mA, $T_A = Full Range (See Figure)$	32)		4	12	mV
$\frac{\Delta V_{REF}}{\Delta V_{Z}}$	Ratio of the Change in Reference Voltage to the Change in Cathode Voltage	I_Z = 10 mA (see Figure 33) V_Z from V_{REF} to 6 V R_1 = 10 kΩ, R_2 = ∞ and 2.6 kΩ			-1.5	-2.7	mV/V
I _{REF}	Reference Input Current	R_1 = 10 kΩ, R_2 = ∞ I_1 = 10 mA (see Figure 33)			0.15	0.50	μΑ
∝I _{REF}	Deviation of Reference Input Current over Temperature	$R_1 = 10 \text{ k}\Omega, R_2 = \infty,$ $I_1 = 10 \text{ mA}, T_A = \text{Full Range}$	(see Figure 33)		0.05	0.3	μΑ
I _{Z(MIN)}	Minimum Cathode Current for Regulation	V _Z = V _{REF} (see Figure 32)			55	80	μΑ
I _{Z(OFF)}	Off-State Current	$V_Z = 6 \text{ V}, V_{REF} = 0 \text{V} \text{ (see Figure 34)}$			0.001	0.1	μΑ
r _Z	Dynamic Output Impedance (2)	$V_Z = V_{REF}$, $I_Z = 0.1$ mA to 15mA Frequency = 0 Hz (see <i>Figure 32</i>)			0.25	0.4	Ω

Deviation of reference input voltage, V_{DEV}, is defined as the maximum variation of the reference input voltage over the full temperature range. See the following:



The average temperature coefficient of the reference input voltage,
$${}_{\alpha}V_{REF}$$
, is defined as:
$${}_{\infty}V_{REF} \frac{ppm}{{}^{\circ}C} = \frac{\pm \left(\frac{V_{Max} - V_{Min}}{V_{REF}(at\ 25{}^{\circ}C)}\right)10^6}{T_2 - T_1} = \frac{\pm \left(\frac{V_{DEV}}{V_{REF}(at\ 25{}^{\circ}C)}\right)10^6}{T_2 - T_1}$$

Where: $T_2 - T_1$ = full temperature change. ${}^{\sim}V_{REF}$ can be positive or negative depending on whether the slope is positive or negative. Example: $V_{DEV} = 6$ mV, $V_{REF} = 1240$ mV, $T_2 - T_1 = 125$ °C. ${}^{\sim}V_{REF} = \frac{\left(\frac{6.0 \text{ mV}}{1240 \text{ mV}}\right) 10^6}{125^{\circ}C} = +39 \text{ ppm} / {}^{\circ}C$

$$\propto V_{REF} = \frac{\left(\frac{6.0 \text{ mV}}{1240 \text{ mV}}\right) 10^6}{125^{\circ}\text{C}} = +39 \text{ ppm} / {^{\circ}\text{C}}$$

The dynamic output impedance, rz, is defined as:

$$r_Z = \frac{\Delta v_Z}{\Delta l_Z}$$

When the device is programmed with two external resistors, R1 and R2, (see Figure 33), the dynamic output impedance of the overall circuit, rz, is defined as:

$$r_Z = \frac{\Delta V_Z}{\Delta I_Z} \cong \left[r_Z \left(1 + \frac{R1}{R2} \right) \right]$$

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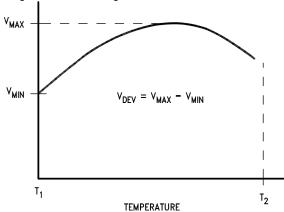


7.10 LMV431BI Electrical Characteristics

 $T_{\Delta} = 25^{\circ}C$ unless otherwise specified

SYMBOL	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V	Deference Voltage	$V_Z = V_{RFF}$, $I_Z = 10 \text{ mA}$	T _A = 25°C	1.234	1.24	1.246	V
V_{REF}	Reference Voltage	(See Figure 32)	T _A = Full Range	1.224		1.259	V
V _{DEV}	Deviation of Reference Input Voltage Over Temperature ⁽¹⁾	$V_Z = V_{REF}$, $I_Z = 10$ mA, $T_A = Full Range$ (See Figure	32)		6	20	mV
$\frac{\Delta V_{REF}}{\Delta V_{Z}}$	Ratio of the Change in Reference Voltage to the Change in Cathode Voltage	I_Z = 10 mA (see Figure 33) V_Z from V_{REF} to 6V R_1 = 10 kΩ, R_2 = ∞ and 2.6 kΩ			-1.5	-2.7	mV/V
I _{REF}	Reference Input Current	$R_1 = 10 \text{ k}\Omega, R_2 = \infty$ $I_1 = 10 \text{ mA (see Figure 33)}$			0.15	0.50	μΑ
∝I _{REF}	Deviation of Reference Input Current over Temperature	R_1 = 10 kΩ, R_2 = ∞, I_1 = 10 mA, T_A = Full Range (see Figure 33)			0.1	0.4	μΑ
$I_{Z(MIN)}$	Minimum Cathode Current for Regulation	V _Z = V _{REF} (see Figure 32)			55	80	μΑ
$I_{Z(OFF)}$	Off-State Current	V _Z = 6 V, V _{REF} = 0 V (see Figure 34)			0.001	0.1	μΑ
r _Z	Dynamic Output Impedance (2)	$V_Z = V_{REF}$, $I_Z = 0.1$ mA to 15 mA Frequency = 0 Hz (see Figure 32)			0.25	0.4	Ω

Deviation of reference input voltage, V_{DEV} , is defined as the maximum variation of the reference input voltage over the full temperature range. See the following:



The average temperature coefficient of the reference input voltage,
$${}^{\sim}V_{REF}$$
, is defined as:
$${}^{\sim}V_{REF} \frac{ppm}{{}^{\circ}C} = \frac{\pm \left(\frac{V_{Max} - V_{Min}}{V_{REF}(at\ 25{}^{\circ}C)}\right) 10^6}{T_2 - T_1} = \frac{\pm \left(\frac{V_{DEV}}{V_{REF}(at\ 25{}^{\circ}C)}\right) 10^6}{T_2 - T_1}$$

Where: $T_2 - T_1$ = full temperature change. ${}^{\omega}V_{REF}$ can be positive or negative depending on whether the slope is positive or negative. Example: $V_{DEV} = 6$ mV, $V_{REF} = 1240$ mV, $T_2 - T_1 = 125$ °C. ${}^{\omega}V_{REF} = \frac{\left(\frac{6.0 \text{ mV}}{1240 \text{ mV}}\right) 10^6}{125 \text{ °C}} = +39 \text{ ppm} \text{ / °C}}$

$$\propto V_{REF} = \frac{\left(\frac{6.0 \text{ mV}}{1240 \text{ mV}}\right) 10^6}{125^{\circ}\text{C}} = +39 \text{ ppm} / {^{\circ}\text{C}}$$

(2) The dynamic output impedance, r_Z, is defined as:

$$r_Z = \frac{\Delta v_Z}{\Delta l_Z}$$

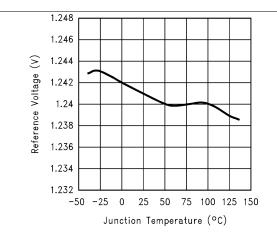
When the device is programmed with two external resistors, R1 and R2, (see Figure 33), the dynamic output impedance of the overall circuit, rz, is defined as:

$$r_Z = \frac{\Delta V_Z}{\Delta I_Z} \cong \left[r_Z \left(1 + \frac{R1}{R2} \right) \right]$$

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7.11 Typical Performance Characteristics

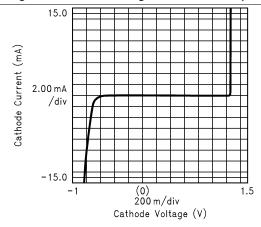


180 (nA) 170 160 Reference Current 150 140 130 120 110 100 -50 -25 25 50 75 100 Junction Temperature (°C)

190

Figure 1. Reference Voltage vs. Junction Temperature

Figure 2. Reference Input Current vs. Junction Temperature



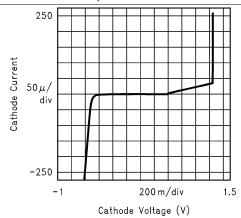
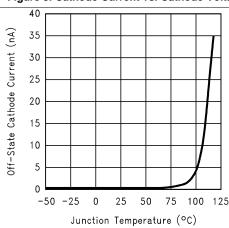


Figure 3. Cathode Current vs. Cathode Voltage 1

Figure 4. Cathode Current vs. Cathode Voltage 2



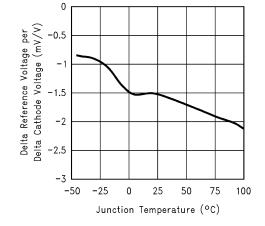
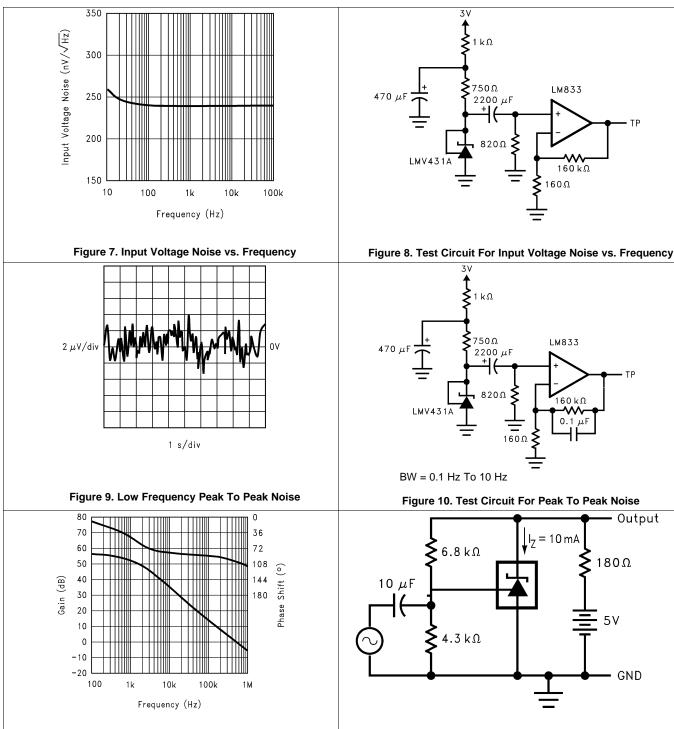


Figure 5. Off-State Cathode Current vs. Junction Temperature

Figure 6. Delta Reference Voltage Per Delta Cathode Voltage vs. Junction Temperature

TEXAS INSTRUMENTS

Typical Performance Characteristics (continued)



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Figure 11. Small Signal Voltage Gain And Phase Shift vs.

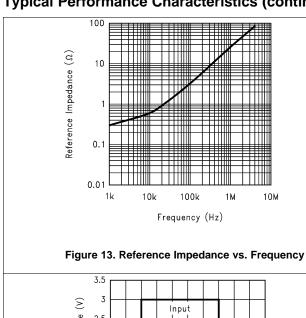
Frequency

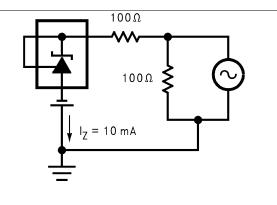
Figure 12. Test Circuit For Voltage Gain And Phase Shift vs.

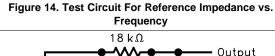
Frequency

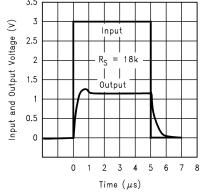


Typical Performance Characteristics (continued)









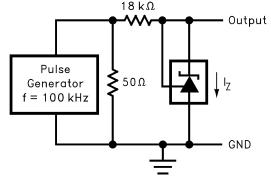
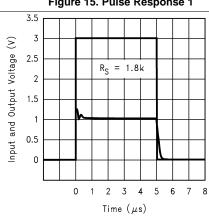


Figure 15. Pulse Response 1

Figure 16. Test Circuit For Pulse Response 1



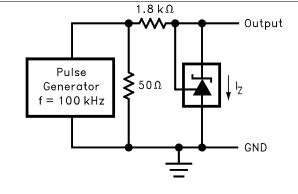
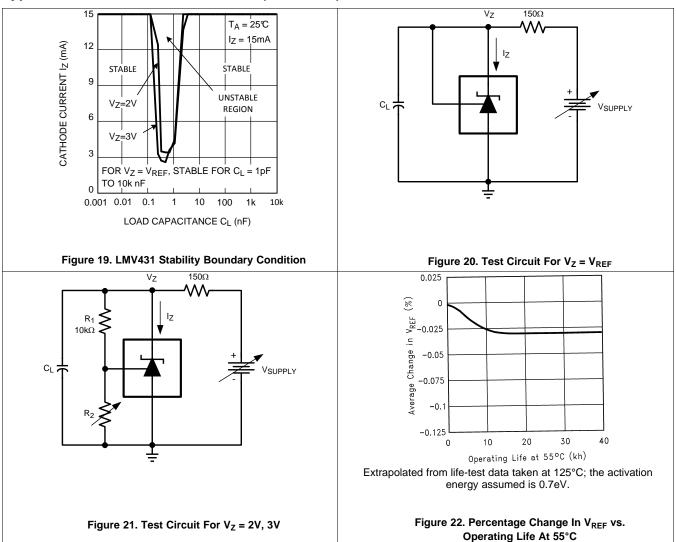


Figure 17. Pulse Response 2

Figure 18. Test Circuit For Pulse Response 2



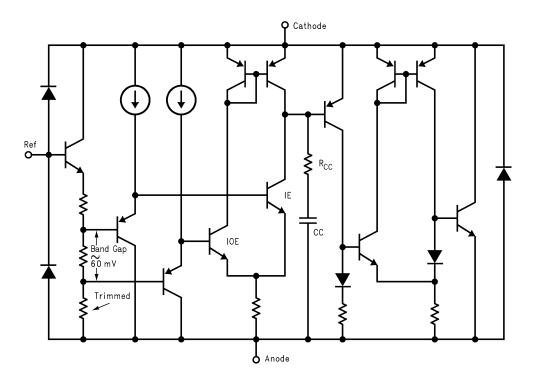
Typical Performance Characteristics (continued)





8 Detailed Description

8.1 Functional Block Diagram





9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Typical Application

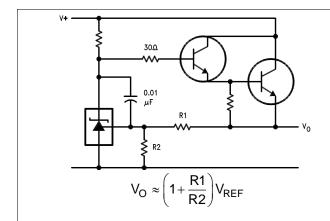


Figure 23. Series Regulator

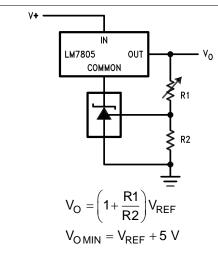


Figure 24. Output Control of a Three-Terminal Fixed Regulator

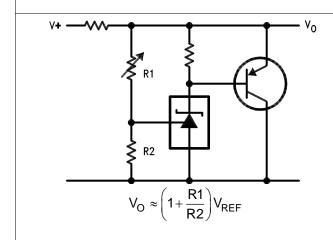


Figure 25. Higher Current Shunt Regulator

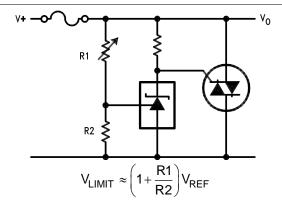


Figure 26. Crow Bar

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Typical Application (continued)

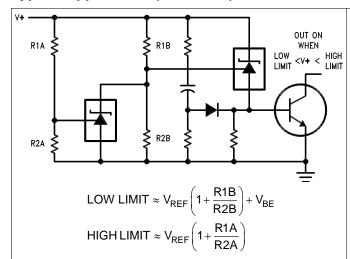


Figure 27. Overvoltage/Undervoltage Protection Circuit

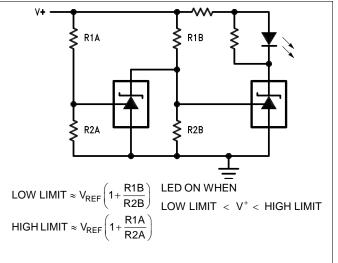
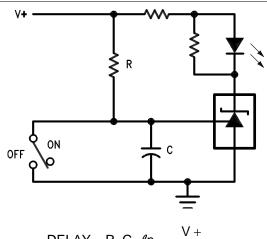
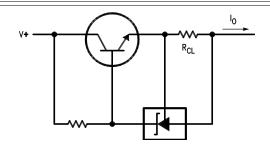


Figure 28. Voltage Monitor



 $DELAY = R \cdot C \cdot \ell n \frac{V +}{(V^+) - V_{REF}}$

Figure 29. Delay Timer



$$_{O} = \frac{V_{REF}}{R_{CL}}$$

Figure 30. Current Limiter or Current Source

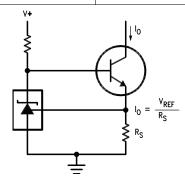
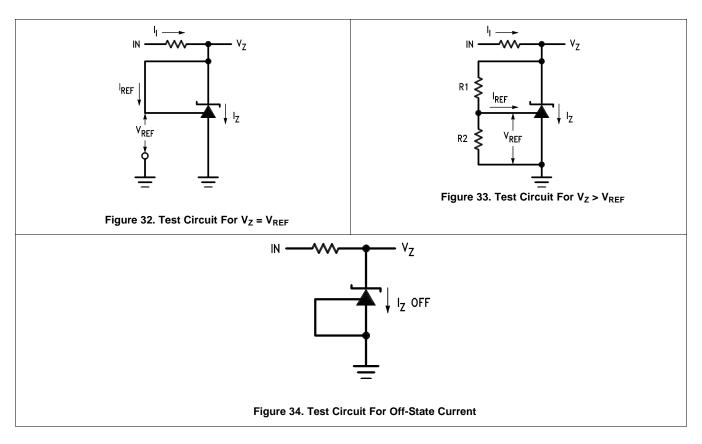


Figure 31. Constant Current Sink



9.2 DC/AC Test Circuit



10 Device and Documentation Support

10.1 Documentation Support

10.1.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
LMV431	Click here	Click here	Click here	Click here	Click here
LMV431A	Click here	Click here	Click here	Click here	Click here
LMV431B	Click here	Click here	Click here	Click here	Click here

10.2 Trademarks

All trademarks are the property of their respective owners.

10.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

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10.4 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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11-Dec-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		-		•	(2)	(6)	(3)		(4/5)	
LMV431ACM5	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-40 to 85	N09A	
LMV431ACM5/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N09A	Samples
LMV431ACM5X/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N09A	Samples
LMV431AIM5	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-40 to 85	N08A	
LMV431AIM5/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N08A	Samples
LMV431AIM5X	NRND	SOT-23	DBV	5	3000	TBD	Call TI	Call TI	-40 to 85	N08A	
LMV431AIM5X/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N08A	Samples
LMV431AIMF	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	RLA	
LMV431AIMF/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RLA	Samples
LMV431AIMFX	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 85	RLA	
LMV431AIMFX/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RLA	Samples
LMV431AIZ/LFT3	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		LMV431 AIZ	Samples
LMV431AIZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	LMV431 AIZ	Samples
LMV431BCM5/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		N09C	Samples
LMV431BCM5X/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		N09C	Samples
LMV431BIMF	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	RLB	
LMV431BIMF/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RLB	Samples
LMV431BIMFX/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM -40 to 85		RLB	Samples
LMV431CM5	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	0 to 70	N09B	
LMV431CM5/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	N09B	Samples



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LMV431CM5X/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	N09B	Samples
LMV431CZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	0 to 70	LMV431 CZ	Samples
LMV431IM5	NRND	SOT-23	DBV	5	1000	TBD	Call TI	Call TI	-40 to 85	N08B	
LMV431IM5/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N08B	Samples
LMV431IM5X/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	N08B	Samples
LMV431IZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-40 to 85	LMV431 IZ	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

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Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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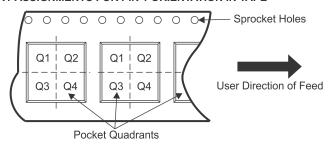
TAPE AND REEL INFORMATION



TAPE DIMENSIONS KO P1 BO W Cavity A0

A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



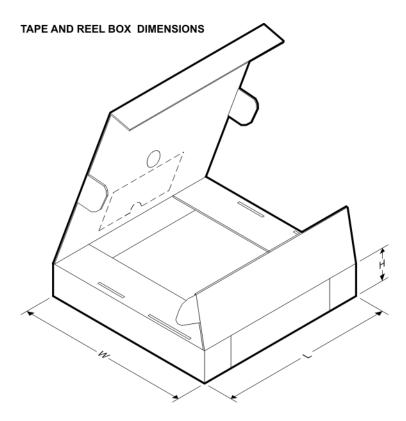
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMV431ACM5	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431ACM5/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431ACM5X/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431AIM5	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431AIM5/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431AIM5X	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431AIM5X/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431AIMF	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LMV431AIMF/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LMV431AIMFX	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LMV431AIMFX/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LMV431BCM5/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431BCM5X/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431BIMF	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LMV431BIMF/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LMV431BIMFX/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LMV431CM5	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431CM5/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

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Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMV431CM5X/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431IM5	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431IM5/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV431IM5X/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMV431ACM5	SOT-23	DBV	5	1000	210.0	185.0	35.0
LMV431ACM5/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LMV431ACM5X/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LMV431AIM5	SOT-23	DBV	5	1000	210.0	185.0	35.0
LMV431AIM5/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LMV431AIM5X	SOT-23	DBV	5	3000	210.0	185.0	35.0
LMV431AIM5X/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LMV431AIMF	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LMV431AIMF/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LMV431AIMFX	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LMV431AIMFX/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LMV431BCM5/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LMV431BCM5X/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0



PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMV431BIMF	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LMV431BIMF/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LMV431BIMFX/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LMV431CM5	SOT-23	DBV	5	1000	210.0	185.0	35.0
LMV431CM5/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LMV431CM5X/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LMV431IM5	SOT-23	DBV	5	1000	210.0	185.0	35.0
LMV431IM5/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LMV431IM5X/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



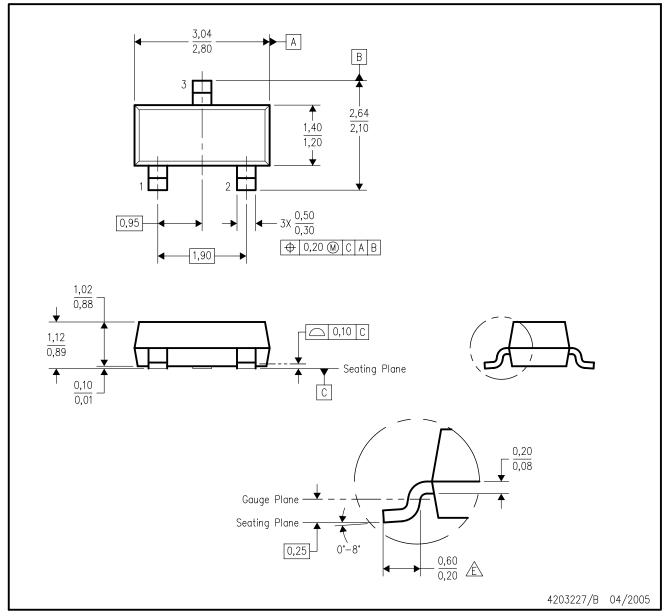
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



DBZ (R-PDSO-G3)

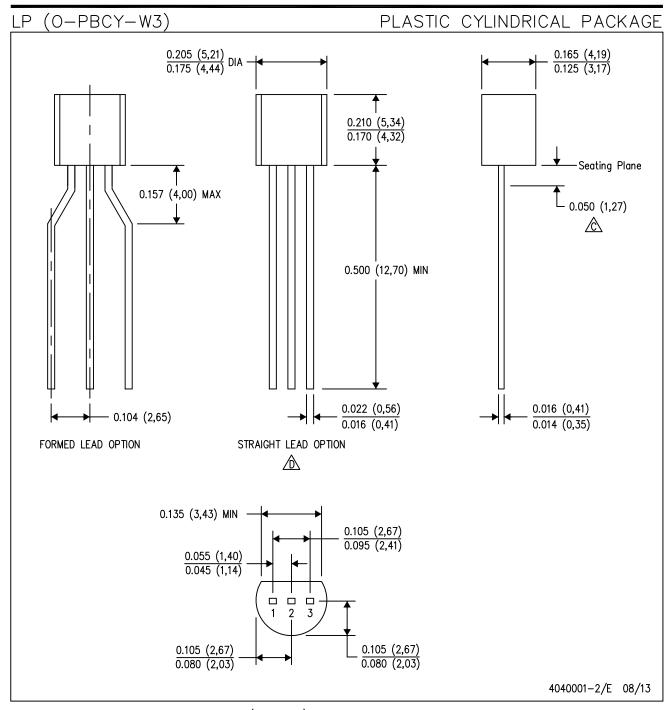
PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Lead dimensions are inclusive of plating.
- D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
- Falls within JEDEC TO-236 variation AB, except minimum foot length.





NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Lead dimensions are not controlled within this area.

Falls within JEDEC TO−226 Variation AA (TO−226 replaces TO−92).

E. Shipping Method:

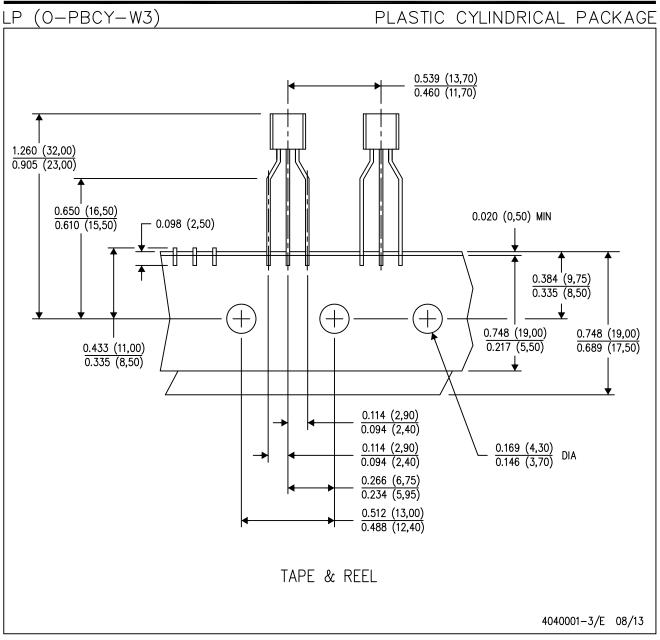
Straight lead option available in bulk pack only.

Formed lead option available in tape & reel or ammo pack.

Specific products can be offered in limited combinations of shipping mediums and lead options.

Consult product folder for more information on available options.





NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Tape and Reel information for the Formed Lead Option package.

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